

IMPERFECT INTERFACES WITH UNILATERAL CONDITIONS: THEORETICAL AND NUMERICAL STUDY

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Adhesive bonding is an assembly technique often used in structural mechanics. In bonded composite structures, the thickness of the glue is much smaller than the other dimensions. In this presentation, numerical strategies are presented to simulate the solid/solid interface behaviour. A particular attention will be paid to take an unilateral condition into consideration to avoid penetration. A first result of the paper is that it is possible to apply a methodology based on asymptotic expansions to this kind of material. Then, a finite element method, using a Nitsche's method to take into account the unilateral contact condition [1, 3], is introduced to solve both the initial problem, considering the thin layer and the limit problem, approximating the thin layer behaviour with contact conditions.

Numerical results are provided to show the capabilities of the procedure, especially in the case of graded materials.

REFERENCES

- [1] S. Dumont, F. Lebon, R. Rizzoni, Imperfect interfaces with graded materials and unilateral conditions: theoretical and numerical study, *Mathematics and Mechanics of Solids*, 1–16, DOI: 10.1177/1081286517732826.
- [2] G. Udupa, S.S. Rao and K. Gangadharan. Functionally graded composite materials: An overview. *Proc Mater Sci* 2014; 5:1291–1299.
- [3] F. Chouly, P. Hild. A Nitsche-based method for unilateral contact problems: numerical analysis. *SIAM Journal on Numerical Analysis*, Society for Industrial and Applied Mathematics, 2013, 51 (2), p. 1295-1307.